




Product and Process Change Notice

PCN No.	PCN03054	PCN Date	10/18/2022	Effective Date	10/18/2022
Title	Qualification of ChipMos as an additional Assembly Site for 48 ball BGA Package				

Type: Minor																							
Everspin is adding ChipMos as an additional Assembly Site for 48 ball BGA Package.																							
Reason For Change																							
Improved manufacturing efficiency and capacity at assembly site.																							
Affected Products																							
<table border="1"> <thead> <tr> <th>Part Number</th> <th>Description</th> </tr> </thead> <tbody> <tr> <td>MR4A08BCMA35</td> <td>Industrial Temp</td> </tr> <tr> <td>MR4A08BMA35</td> <td>Commercial Temp</td> </tr> <tr> <td>MR4A08BCMA35R</td> <td>Industrial Temp, T&R</td> </tr> <tr> <td>MR4A08BMA35R</td> <td>Commercial Temp, T&R</td> </tr> </tbody> </table>			Part Number	Description	MR4A08BCMA35	Industrial Temp	MR4A08BMA35	Commercial Temp	MR4A08BCMA35R	Industrial Temp, T&R	MR4A08BMA35R	Commercial Temp, T&R											
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Impact on Form, Fit, Function, Quality or Reliability																							
No Impact																							
Proposed First Ship Date for Change:																							
November 18, 2022																							
Key Material Differences																							
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Product Identifier																							
Assembly site code = H for ChipMos Taiwan																							
Supplier Qual Plan Schedule and Results																							
Site package qualification is complete and all Everspin requirements met. QUA03055 QR																							
Date Qualification Samples Are Available:																							
Samples are generally available now but please request your specific part number to your Everspin Sales contact.																							
Acceptance of Change																							
Everspin will consider this change accepted unless specific conditions for acceptance are provided in writing within 30 days of receipt of this notice.																							

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PCN No.	PCN03054	PCN Date	10/12/2022	Effective Date	10/10/2022
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Contact Information		Sample Information <input checked="" type="checkbox"/> Samples Available Now
Everspin Quality Everspin Technologies (480) 347-1084 bonnie.paro@everspin.com		Contact Everspin sales: http://www.everspin.com/contact-us-everspin-technologies If using the on-line sample request, please refer to this PCN # to receive samples.
Originator		
<u>Date</u> 10/17/2022	<u>Title</u> Senior Quality Engineer	<u>Name</u> Bonnie S. Paro 
Approval and Release		
<u>Date</u> 10/17/2022	<u>Title</u> VP of Fab Ops & Quality	<u>Name</u> Khaldoun Barakat 
<u>Date</u> 10/17/2022	<u>Title</u> VP of Backend Operations	<u>Name</u> Amit Shah 
<u>Date</u> 10/13/2022	<u>Title</u> Sr. Director of Marketing	<u>Name</u> Joe O'Hare 